



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IRLZ34NPBF	<b>Issued</b>	21. July 2021
<b>MA#</b>	MA005540933		
<b>Package</b>	PG-TO220-3-904	<b>Weight*</b>	2368.98 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	4.386	0.19	0.19	1851	1851
chip_2	inorganic material	silicon	7440-21-3	4.386	0.19	0.19	1851	1851
chip_3	inorganic material	silicon	7440-21-3	4.386	0.19	0.19	1851	1851
leadframe	inorganic material	phosphorus	7723-14-0	0.499	0.02		211	
	non noble metal	iron	7439-89-6	1.664	0.07		702	
	non noble metal	copper	7440-50-8	1,661.709	70.14	70.23	701447	702360
wire	non noble metal	aluminium	7429-90-5	1.754	0.07	0.07	740	740
encapsulation	organic material	carbon black	1333-86-4	3.249	0.14		1371	
	plastics	epoxy resin	-	129.950	5.49		54855	
	inorganic material	silicondioxide	60676-86-0	516.551	21.80	27.43	218049	274275
leadfinish	non noble metal	tin	7440-31-5	25.685	1.08	1.08	10842	10842
solder	non noble metal	tin	7440-31-5	0.295	0.01		125	
	noble metal	silver	7440-22-4	0.369	0.02		156	
	non noble metal	lead	7439-92-1	14.094	0.59	0.62	5949	6230
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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